ON Semiconductor®

Initial Product/Process Change Notification

Document #:IPCN23582Y
Issue Date:27 Nov 2020

Title of Change:	Replace Hitachi mold compound with Hysol compound for Medical devices at Leshan, China
Proposed First Ship date:	12 Apr 2021 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Chengrong Sun <c.r.sun@lps.com.cn> or Hannah Zhang <Hannah.Zhang@lps.com.cn>
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	Products (listed in this PCN) assembled with Hysol compound in ON Semiconductor facility, Leshan, China, will have a Finish Good Date Code from about Week 15, 2021 or greater
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
Leshan Phoenix Semiconductor, China	None

Change Description :

Changing description is listed in below table.

Reliability Qualification and electrical characterization will be performed during qualification, and can be shared after issuing Final PCN.

	Before Change Description	After Change Description
Mold Compound	Hitachi GE200F	Hysol GR640 HV

There is no product marking change as a result of this change.

Qualification Plan:

QV DEVICE NAME: 0IMD4-001-XTP, MDNSD16F3T5G
0IMT1-001-XTP, 0IMDD-001-XTP
0IMD1-001-XTP, 0IMD6-001-XTP
PACKAGE: SOT563, SOD1123, SC74, SC70, SOD923, SOT723

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta= 150°C, 100% max rated V	2016 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Ti=100°C On/off = 2min	15000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
RSH	JESD22- B106	Ta= 265C, 10 sec	
SD	JSTD002	Ta= 245C, 5 sec	

Estimated date for qualification completion: 30 January 2021

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
0IMD1-001-XTP	NA
0IMD6-001-XTP	NA
MDNSD16F3T5G	NA